

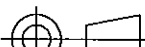
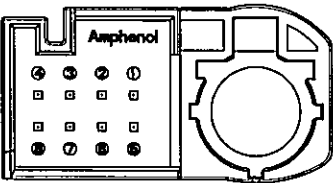
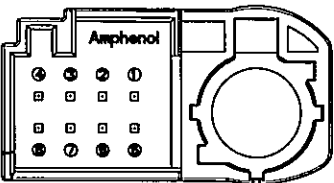
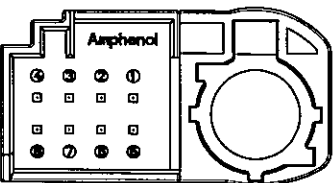
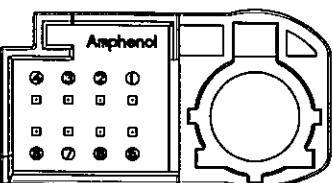
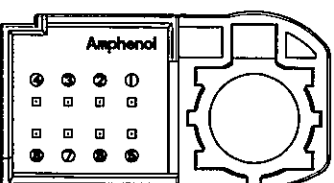
UNLESS OTHERWISE SPECIFIED TOLERANCES		APPROVAL		DATE		Amphenol	
U.S.	METRIC	DRAWN	Koko Yang	11/21/16			
.X +/-	0.50	CHECKED	<i>[Signature]</i>		TITLE HSD + 8pos MQS R/A plug connector NORTH LOCATION		
.XX +/-	0.20	CHECKED					
.XXX +/-	0.10	DRAWING FILE :		SIZE DRAWING NO. A4 HSD NXRP PCB 8X			
FRACTIONS +/-	5°	ANGLE OF PROJECTION					
FOR MATERIALS AND FINISHES SEE MATERIALS				REV. 4			
REMOVE SHARP EDGES							
DIMENSIONS							
U.S.	INCHES						
METRIC	MM	SCALE		2:1	SHEET 1 OF 2		

Table 1
keys and colors

				
Coding A graphite black sim. RAL9011	Coding B natural sim. RAL9001	Coding C light blue sim. RAL5012	Coding D claret violet sim. RAL4004	Coding Z water blue sim. RAL5021

Notes:

1.Material and plating:

Component	Material	Plating
Housing:	PA4T, UL94-V0, color see table1	
Dielectric:	LCP, UL94-V0, color black	
Outer contact (PCB):	Zinc alloy	Tin, 2-6um, over nickel
Cover:	Stainless Steel.	
HSD contact:	Copper alloy	Gold, 0.15um (interface); gold flash(PCB)
MQS contact:	Copper alloy	Tin, 2-6um, over nickel

2.Electrical data, HSD side:

Impedance, even mode	$\approx 32 \Omega$ common mode only
Impedance, differential mode	100 Ω differential signaling, for one pair or quad cable shielded
Frequency	DC to 2.0 GHz
Return loss	≥ 20 dB to 1.0 GHz ≥ 17 dB to 2.0 GHz
Insertion loss	≤ 0.1 dB @ 1.0 GHz
Skew (between signal contacts)	≤ 20 psec. (can be reduced by layout)
Nearend-Crosstalk	≤ 30 dB
Farend-Crosstalk	≤ 35 dB
Insulation resistance	$\geq 1 \times 10^3$ M Ω
Signal contact resistance	≤ 10 m Ω
Outer contact resistance	≤ 7.5 m Ω
Test voltage	500 V rms
Working voltage	100 V rms
Test current capability at 80°C	≤ 1.5 A DC
Test current capability at 80°C MQS pins	≤ 5.0 A DC (dependent on mating connector and cable)

3.Mechanical data, HSD side:

Mating cycles	≥ 25
Engagement force each contact	≤ 30 N
Disengagement force each contact	≥ 5 N
Retention force latch	≥ 110 N
Coding efficiency	≥ 80 N

4.Environmental data:

Temperature range	-40°C to +105°C
Thermal shock	DIN IEC 60068-2-14 Test Na
Temperature and humidity	USCar 2 - 4 5.6.2
Vibration (Random)	DIN IEC 60068-2-64
Mechanical Shock	DIN IEC 60068-2-27
High-Temp. Exposure	DIN IEC 60068-2-2
Soldering profile	acc. to IEC 60068-2-58; Group 3&4
2011/65/EU (RoHS)	compliant

5.Packing

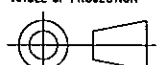
Standard	100 pcs in tape & reel
Weight	12.97 g/pce

6. Order P/N system:

HSD NXRP PCB 8X

Coding: _____
See table 1

Packing method:
A- Packing by tape & reel
B- Packing by tray
C- Single Packing

UNLESS OTHERWISE SPECIFIED TOLERANCES U.S. METRIC .X +/- 0.50 .XX +/- 0.25 .XXX +/- 0.10 FRACTIONS +/- 1/16 ANGLES +/- 1° FOR MATERIALS AND FINISHES SEE NOTES REMOVE SHARP EDGES DIMENSIONS U.S. INCHES METRIC MM		APPROVAL DRAWN Kaka Yang CHECKED Heng DATE 11/21/16 DRAWING FILE: HSD_NXRP_PCB_8X.dwg ANGLE OF PROJECTION 	DATE 11/21/16 TITLE HSD + 8pos MQS R/A plug connector NORTH LOCATION SIZE A4 DRAWING NO. HSD NXRP PCB 8X SCALE 2:1 SHEET 2 OF 2	REV. 4
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